

# 具有 **SpeakerGuard™** 的 TPA3111D1-Q1 10W 无滤波器单声道 D 类音频功率放大器

## 1 特性

- 汽车电子 应用认证
- 具有符合 AEC-Q100 的下列结果：
  - 器件温度 1 级：-40°C 至 125°C 的环境运行温度范围
  - 器件人体放电模型 (HBM) 静电放电 (ESD) 分类等级 H2
  - 器件 CDM ESD 分类等级 C2
- 由 12V 电源供电时，10W 功率进入 8Ω 负载（在 10% 总谐波失真 (THD)+N 时）
- 由 8V 电源供电时，7W 功率进入 4Ω 负载（在 10% THD+N 时）
- 进入 8Ω 负载的 94% 高效 D 类运行免除了对散热片的需要
- 宽电源电压范围允许在 8 至 26 V 的电压范围内工作
- 无滤波器运行
- **SpeakerGuard™** 扬声器保护包括可调节功率限制器和 DC 保护
- 直通式外引脚简化了电路板布局设计
- 具有自动恢复选项的稳健耐用引脚至引脚短路保护和热保护
- 出色的 THD+N 和无爆音性能
- 4 个可选固定增益设置
- 差分输入

## 2 应用

- 针对混合动力汽车/电动汽车 (HEV/EV) 的汽车噪音生成
- 汽车紧急呼叫 (eCall) 系统
- 汽车信息娱乐系统（音响主机、仪表盘、远程信息处理、导航）
- 汽车连接网关
- 专业音频设备 (PA 扬声器、工作室耳机、高性能放大器、高级麦克风)
- 航空与航天音频系统

## 3 说明

TPA3111D1-Q1 器件是一款用于驱动桥接式扬声器的 10W 高效 D 类音频功率放大器。高级 EMI 抑制技术能够在满足 EMC 要求的同时使用户能够在输出端上使用价格低廉的磁珠滤波器。**SpeakerGuard™** 保护电路系统包含一个可调节功率限制器和一个直流检测电路。可调节功率限制器允许用户设置低于芯片电源电压的虚拟电压轨，以便限制通过扬声器的电量。直流检测电路可以测量 PWM 信号的频率和振幅，如果输入电容器受损或者输入端存在短路，它就会关断输出级。

TPA3111D1-Q1 可驱动一个低至 4Ω 的单声道扬声器。播放音乐时，TPA3111D1-Q1 器件大于 90% 的高效率免除了对于外部散热片的需要。

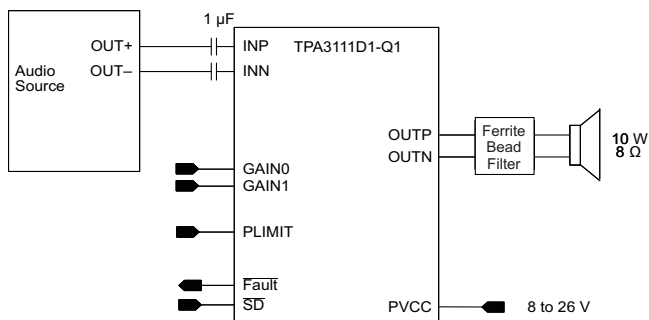
输出受到完全的保护以防止到 GND, V<sub>CC</sub>, 和输出到输出的短接。短路保护和热保护均含有自动恢复功能。

### 器件信息(1)

器件型号	封装	封装尺寸 (标称值)
TPA3111D1-Q1	HTSSOP (28)	9.70mm × 4.40mm

(1) 要了解所有可用封装，请参见数据表末尾的可订购产品附录。

### 简化应用示意图



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## 4 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

### Changes from Revision D (August 2015) to Revision E Page

- Updated active-low pin names to include the overbar throughout the document ..... 10

### Changes from Revision C (December 2012) to Revision D Page

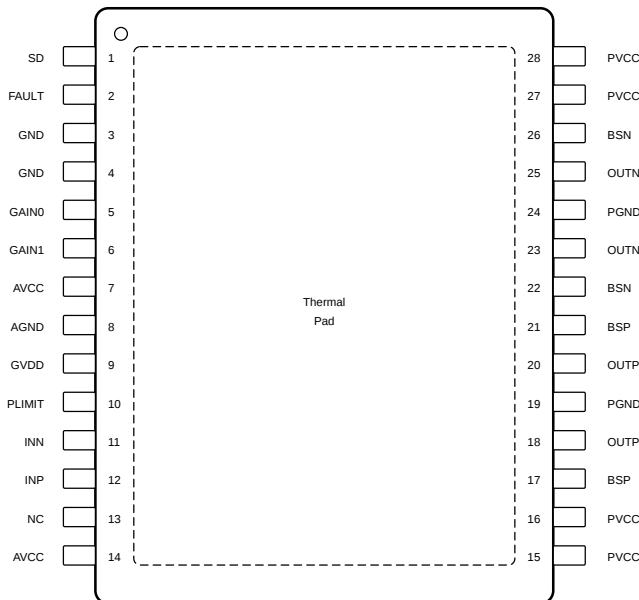
- 已添加 *ESD* 额定值表，特性说明部分，器件功能模式，应用和实施部分，电源相关建议部分，布局部分，器件和文档支持部分以及机械、封装和可订购信息部分 ..... 1

### Changes from Revision B (September 2012) to Revision C Page

- Changed AEC-Q100-003 to per JESD22-A115 in Abs Max table. .... 4
- Changed  $T_A$  from 25°C to -40°C to 125°C ..... 5
- Changed  $T_A$  from 25°C to -40°C to 125°C ..... 5
- Changed  $T_A$  from 25°C to -40°C to 125°C ..... 6
- Changed  $T_A$  from 25°C to -40°C to 125°C ..... 6

## 5 Pin Configuration and Functions

PWP Package  
28-Pin HSSOP With PowerPAD™  
Top View



### Pin Functions

PIN		TYPE	DESCRIPTION
NAME	NO.		
AGND	8	—	Analog supply ground, connect to the thermal pad.
AVCC	7	P	Analog supply
AVCC	14	P	Connect AVCC supply to this pin
BSN	22, 26	I	Bootstrap I/O for negative high-side FET
BSP	17, 21	I	Bootstrap I/O for positive high-side FET
$\overline{\text{FAULT}}$	2	O	Open drain output used to display short circuit or DC-detect fault status. Voltage compliant to AVCC. Short circuit faults can be set to auto-recovery by connecting $\overline{\text{FAULT}}$ pin to SD pin. Otherwise both short circuit faults and DC-detect faults must be reset by cycling PVCC.
GAIN0	5	I	Gain select least significant bit. TTL logic levels with compliance to AVCC.
GAIN1	6	I	Gain select most significant bit. TTL logic levels with compliance to AVCC.
GND	3, 4	—	Connect to local ground
GVDD	9	O	High-side FET gate drive supply, nominal voltage is 7 V. This pin can also be used as supply for PLIMIT divider. Add a 1- $\mu$ F capacitor to ground at this pin.
INN	11	I	Negative audio input, biased at 3 V.
INP	12	I	Positive audio input, biased at 3 V.
NC	13	—	Not connected
OUTN	23, 25	O	Class-D H-bridge negative output
OUTP	18, 20	O	Class-D H-bridge positive output
PGND	19, 24	—	Power ground for the H-bridges
PLIMIT	10	I	Power limit level adjust. Connect directly to GVDD pin for no power limiting. Add a 1- $\mu$ F capacitor to ground at this pin.
PVCC	15, 16, 27, 28	P	Power supply for H-bridge. PVCC pins are also connected internally.
$\overline{\text{SD}}$	1	I	Shutdown logic input for audio amplifier (LOW = outputs Hi-Z, HIGH = outputs enabled). TTL logic levels with compliance to AVCC.

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	AVCC, PVCC	-0.3	30	V
V <sub>I</sub>	Interface pin voltage	$\overline{SD}$ , $\overline{FAULT}$ , GAIN0, GAIN1, AVCC <sup>(2)</sup>	-0.3	V <sub>CC</sub> + 0.3 V	V
		PLIMIT		< 10	V/ms
		INN, INP	-0.3	GVDD + 0.3	V
Continuous total power dissipation			See <a href="#">Thermal Information</a>		
R <sub>L</sub>	Minimum load resistance	BTL		3.2	
T <sub>A</sub>	Operating free-air temperature range		-40	125	°C
T <sub>J</sub>	Operating junction temperature range <sup>(3)</sup>		-40	150	°C
T <sub>stg</sub>	Storage temperature range		-65	150	°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operations of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The voltage slew rate of these pins must be restricted to no more than 10 V/ms. For higher slew rates, use a 100-kΩ resistor in series with the pins, per application note [SLUA626](#).
- (3) The TPA3111D1-Q1 incorporates an exposed thermal pad on the underside of the chip. This acts as a heatsink, and it must be connected to a thermally dissipating plane for proper power dissipation. Failure to do so may result in the device going into thermal protection shutdown. See TI Technical Brief [SLMA002](#) for more information about using the PowerPAD.

### 6.2 ESD Ratings

		VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human-body model (HBM), per AEC Q100-002 <sup>(1)</sup>	±4000
		Charged-device model (CDM), per AEC Q100-011	±250
		Machine model	±200

- (1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	PVCC, AVCC	8	26	V
V <sub>IH</sub>	High-level input voltage	$\overline{SD}$ , GAIN0, GAIN1	2		V
V <sub>IL</sub>	Low-level input voltage	$\overline{SD}$ , GAIN0, GAIN1		0.8	V
V <sub>OL</sub>	Low-level output voltage	$\overline{FAULT}$ , R <sub>PULLUP</sub> = 100 kΩ, V <sub>CC</sub> = 26 V		0.8	V
I <sub>IH</sub>	High-level input current	$\overline{SD}$ , GAIN0, GAIN1, V <sub>I</sub> = 2, V <sub>CC</sub> = 18 V		50	μA
I <sub>IL</sub>	Low-level input current	$\overline{SD}$ , GAIN0, GAIN1, V <sub>I</sub> = 0.8 V, V <sub>CC</sub> = 18 V		5	μA
T <sub>A</sub>	Operating free-air temperature		-40	125	°C

## 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		TPA3111D1-Q1	UNIT
		PWP (HTSSOP)	
		28 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	30.3	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	33.5	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	17.5	°C/W
ψ <sub>JT</sub>	Junction-to-top characterization parameter	0.9	°C/W
ψ <sub>JB</sub>	Junction-to-board characterization parameter	7.2	°C/W
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	0.9	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

## 6.5 DC Characteristics: V<sub>CC</sub> = 24 V

T<sub>A</sub> = -40°C to 125°C, R<sub>L</sub> = 8 Ω (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
V <sub>OS</sub>	Class-D output offset voltage (measured differentially)	V <sub>I</sub> = 0 V, Gain = 36 dB		1.5	15	mV	
I <sub>CC</sub>	Quiescent supply current	$\overline{SD}$ = 2 V, no load, PVCC = 21 V		40		mA	
I <sub>CC(SD)</sub>	Quiescent supply current in shutdown mode	$\overline{SD}$ = 0.8 V, no load, PVCC = 21 V		400		μA	
r <sub>DS(on)</sub>	Drain-source on-state resistance	I <sub>O</sub> = 500 mA, T <sub>J</sub> = 25°C				mΩ	
		High side		240			
		Low side		240			
G	Gain	GAIN1 = 0.8 V	GAIN0 = 0.8 V	19	20	21	dB
			GAIN0 = 2 V	25	26	27	
		GAIN1 = 2 V	GAIN0 = 0.8 V	31	32	33	
			GAIN0 = 2 V	35	36	37	
t <sub>ON</sub>	Turnon time	$\overline{SD}$ = 2 V		10		ms	
t <sub>OFF</sub>	Turnoff time	$\overline{SD}$ = 0.8 V		2		μs	
GVDD	Gate drive supply	I <sub>GVDD</sub> = 2 mA	6.5	6.9	7.3	V	

## 6.6 DC Characteristics: V<sub>CC</sub> = 12 V

T<sub>A</sub> = -40°C to 125°C, R<sub>L</sub> = 8 Ω (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
V <sub>OS</sub>	Class-D output offset voltage (measured differentially)	V <sub>I</sub> = 0 V, Gain = 36 dB		1.5	15	mV	
I <sub>CC</sub>	Quiescent supply current	$\overline{SD}$ = 2 V, no load, PVCC = 12 V		20		mA	
I <sub>CC(SD)</sub>	Quiescent supply current in shutdown mode	$\overline{SD}$ = 0.8 V, no load, PVCC = 12 V		200		μA	
r <sub>DS(on)</sub>	Drain-source on-state resistance	I <sub>O</sub> = 500 mA, T <sub>J</sub> = 25°C				mΩ	
		High side		240			
		Low side		240			
G	Gain	GAIN1 = 0.8 V	GAIN0 = 0.8 V	19	20	21	dB
			GAIN0 = 2 V	25	26	27	
		GAIN1 = 2 V	GAIN0 = 0.8 V	31	32	33	
			GAIN0 = 2 V	35	36	37	
t <sub>ON</sub>	Turnon time	$\overline{SD}$ = 2 V		10		ms	
t <sub>OFF</sub>	Turnoff time	$\overline{SD}$ = 0.8 V		2		μs	
GVDD	Gate drive supply	I <sub>GVDD</sub> = 2 mA	6.5	6.9	7.3	V	
PLIMIT	Output voltage maximum under PLIMIT control	V <sub>PLIMIT</sub> = 2 V; V <sub>I</sub> = 6-V differential	6.75	7.90	8.75	V	

## 6.7 AC Characteristics: $V_{CC} = 24\text{ V}$

 $T_A = -40^\circ\text{C}$  to  $125^\circ\text{C}$ ,  $R_L = 8\ \Omega$  (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$K_{SVR}$	Power supply ripple rejection	200 mV <sub>PP</sub> ripple from 20 Hz–1 kHz, Gain = 20 dB, inputs AC-coupled to AGND		-70		dB
$P_O$	Continuous output power	THD+N $\leq$ 0.1%, $f = 1\text{ kHz}$ , $V_{CC} = 24\text{ V}$		10		W
THD+N	Total harmonic distortion + noise	$V_{CC} = 24\text{ V}$ , $f = 1\text{ kHz}$ , $P_O = 5\text{ W}$ (half-power)		< 0.05%		
$V_n$	Output integrated noise	20 Hz to 22 kHz, A-weighted filter, Gain = 20 dB		65		$\mu\text{V}$
				-80		dBV
	Crosstalk	$V_O = 1\text{ V}_{RMS}$ , Gain = 20 dB, $f = 1\text{ kHz}$		-70		dB
SNR	Signal-to-noise ratio	Maximum output at THD+N < 1%, $f = 1\text{ kHz}$ , Gain = 20 dB, A-weighted		102		dB
$f_{OSC}$	Oscillator frequency		250	310	350	kHz
	Thermal trip point			150		$^\circ\text{C}$
	Thermal hysteresis			15		$^\circ\text{C}$

## 6.8 AC Characteristics: $V_{CC} = 12\text{ V}$

 $T_A = -40^\circ\text{C}$  to  $125^\circ\text{C}$ ,  $R_L = 8\ \Omega$  (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$K_{SVR}$	Supply ripple rejection	200 mV <sub>PP</sub> ripple from 20 Hz–1 kHz, Gain = 20 dB, inputs AC-coupled to AGND		-70		dB
$P_O$	Continuous output power	THD+N $\leq$ 10%, $f = 1\text{ kHz}$ , $R_L = 8\ \Omega$		10		W
$P_O$	Continuous output power	THD+N $\leq$ 0.1%, $f = 1\text{ kHz}$ , $R_L = 4\ \Omega$		10		W
THD+N	Total harmonic distortion + noise	$R_L = 8\ \Omega$ , $f = 1\text{ kHz}$ , $P_O = 5\text{ W}$ (half-power)		< 0.06%		
$V_n$	Output integrated noise	20 Hz to 22 kHz, A-weighted filter, Gain = 20 dB		65		$\mu\text{V}$
				-80		dBV
	Crosstalk	$P_O = 1\text{ W}$ , Gain = 20 dB, $f = 1\text{ kHz}$		-70		dB
SNR	Signal-to-noise ratio	Maximum output at THD+N < 1%, $f = 1\text{ kHz}$ , Gain = 20 dB, A-weighted		102		dB
$f_{OSC}$	Oscillator frequency		250	310	350	kHz
	Thermal trip point			150		$^\circ\text{C}$
	Thermal hysteresis			15		$^\circ\text{C}$

## 6.9 Typical Characteristics

All measurements taken at 1 kHz, unless otherwise noted, using the TPA3110D2EVM, which is available at [ti.com](http://ti.com).

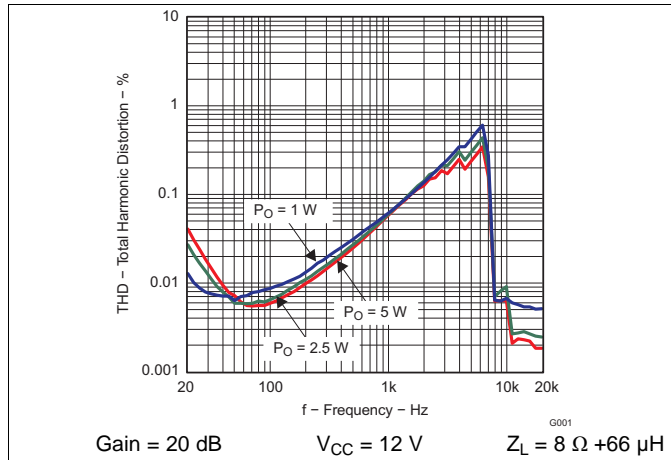


Figure 1. Total Harmonic Distortion vs Frequency

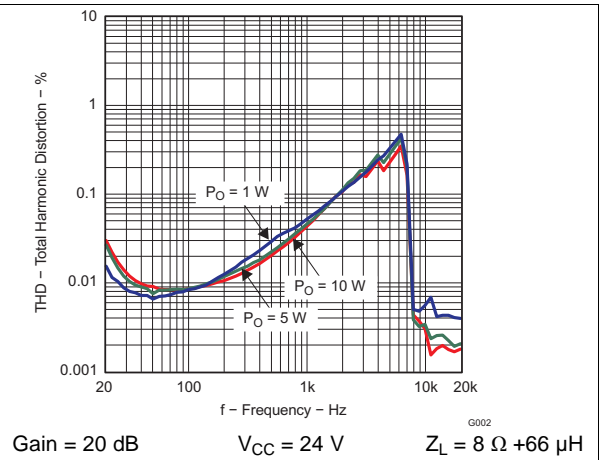


Figure 2. Total Harmonic Distortion vs Frequency

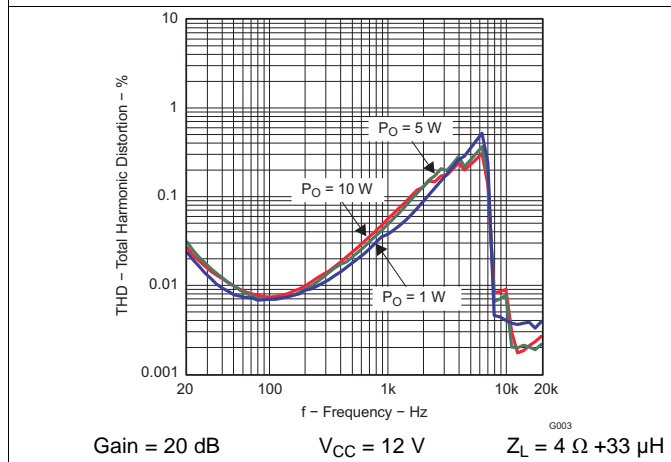


Figure 3. Total Harmonic Distortion vs Frequency

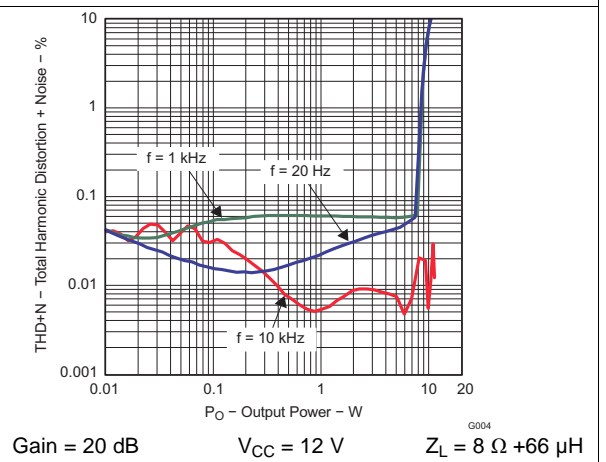


Figure 4. Total Harmonic Distortion + Noise vs Output Power

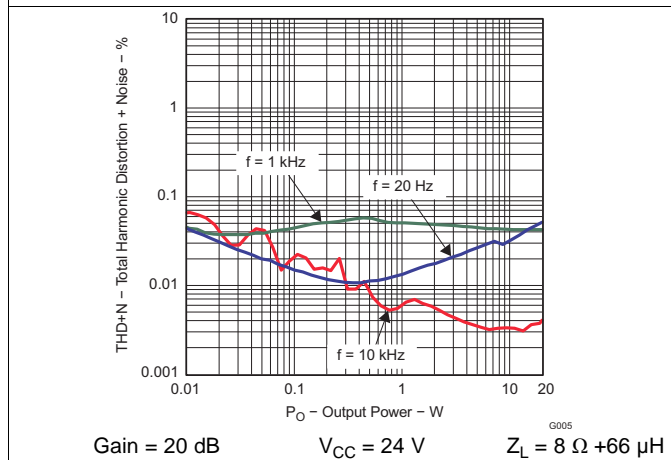


Figure 5. Total Harmonic Distortion + Noise vs Output Power

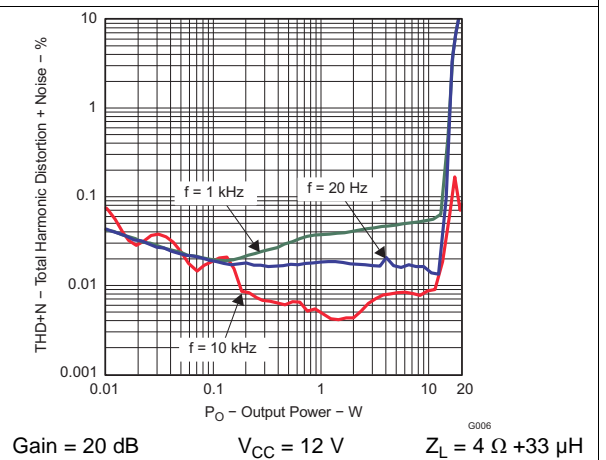
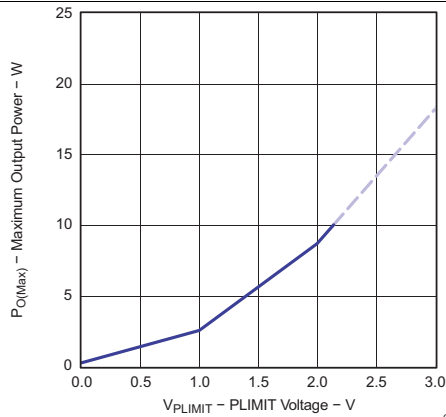


Figure 6. Total Harmonic Distortion + Noise vs Output Power

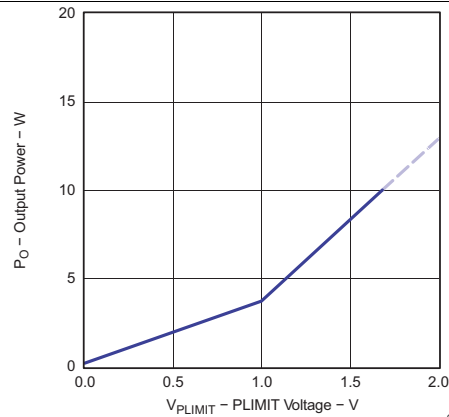
**Typical Characteristics (continued)**

All measurements taken at 1 kHz, unless otherwise noted, using the TPA3110D2EVM, which is available at [ti.com](http://ti.com).



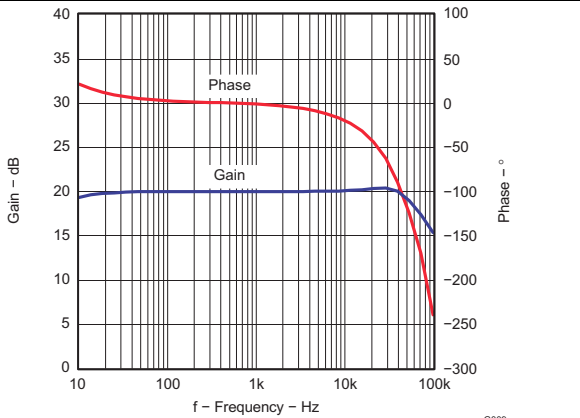
Gain = 20 dB  $V_{CC} = 24\text{ V}$   $Z_L = 8\ \Omega +66\ \mu\text{H}$   
The dashed line represents thermally limited region.

**Figure 7. Maximum Output Power vs PLIMIT Voltage**



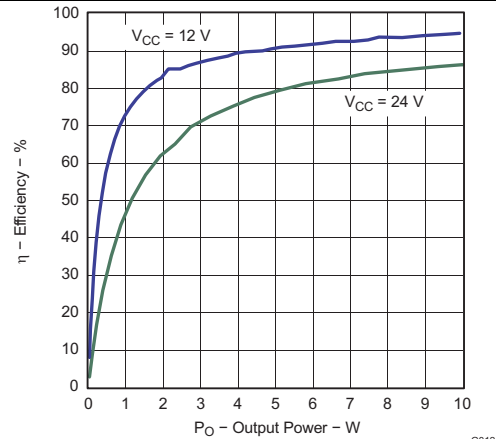
Gain = 20 dB  $V_{CC} = 12\text{ V}$   $Z_L = 4\ \Omega +33\ \mu\text{H}$   
The dashed line represents thermally limited region.

**Figure 8. Output Power vs PLIMIT Voltage**



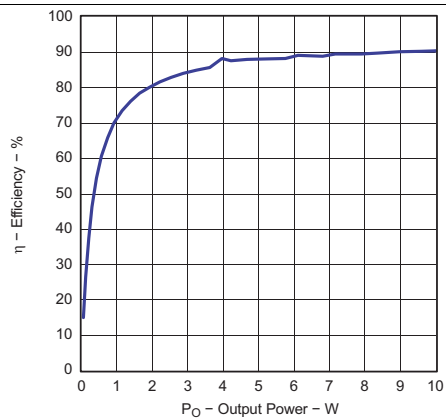
Gain = 20 dB  $V_{CC} = 12\text{ V}$   $Z_L = 8\ \Omega +66\ \mu\text{H}$   
 $C_1 = 1\ \mu\text{F}$   $V_I = 0.1\ \text{V}_{\text{RMS}}$   
Filter = Audio Precision AUX-0025

**Figure 9. Gain/Phase vs Frequency**



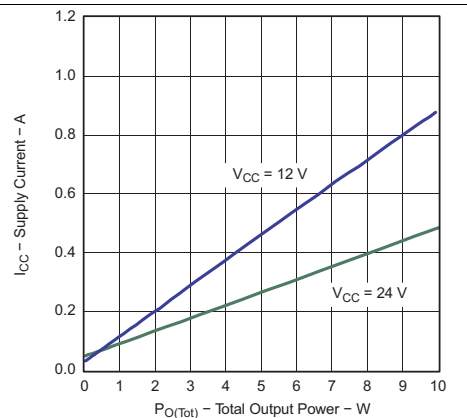
Gain = 20 dB  $Z_L = 8\ \Omega +66\ \mu\text{H}$

**Figure 10. Efficiency vs Output Power**



Gain = 20 dB  $V_{CC} = 12\text{ V}$   $Z_L = 4\ \Omega +33\ \mu\text{H}$

**Figure 11. Efficiency vs Output Power**



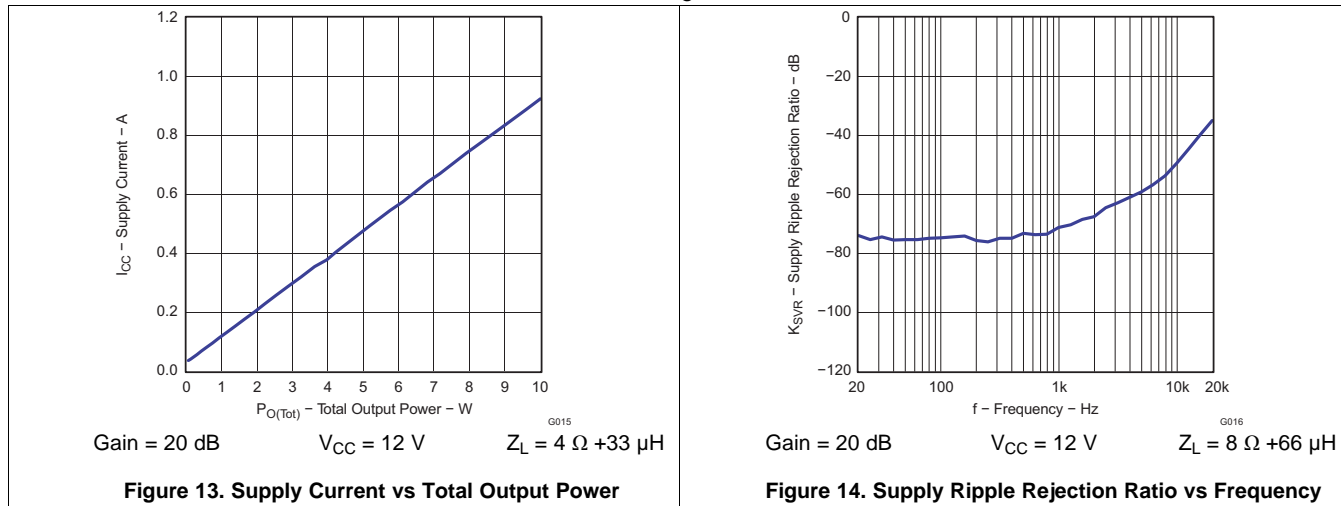
Gain = 20 dB  $Z_L = 8\ \Omega +66\ \mu\text{H}$

**Figure 12. Supply Current vs Total Output Power**



**Typical Characteristics (continued)**

All measurements taken at 1 kHz, unless otherwise noted, using the TPA3110D2EVM, which is available at [ti.com](http://ti.com).



## 7 Detailed Description

### 7.1 Overview

The TPA3111D1-Q1 device is AEC-Q100 qualified with temperature grade 1 (–40°C to 125°C), HBM ESD classification level H2, and CDM ESD classification level C2 (see the [ESD Ratings](#) table). This automotive audio amplifier also features several protection mechanisms as follows:

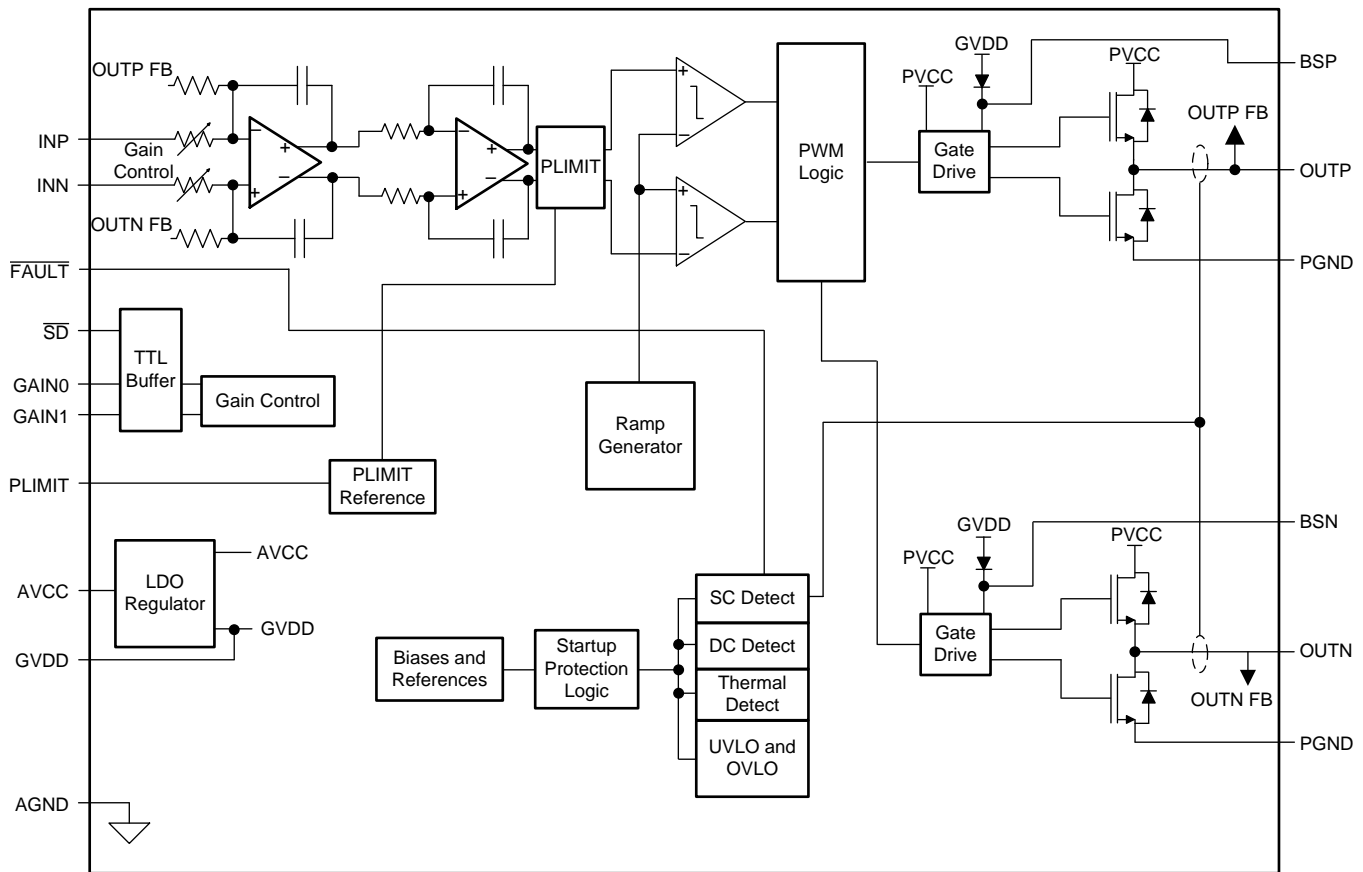
- DC-Current Detection:
  - The TPA3111D1-Q1 device protects speakers from DC current by reporting a fault on the  $\overline{\text{FAULT}}$  pin and turning the amplifier outputs to a Hi-Z state when a DC current is detected. The PVCC supply must be cycled to clear this fault.
- Short-Circuit Protection and Automatic Recovery:
  - The TPA3111D1-Q1 device has short circuit protection from the output pins to VCC, GND, or to each other. If a short circuit is detected, it is reported on the  $\overline{\text{FAULT}}$  pin and the amplifier outputs switch to a Hi-Z state. The fault can be cleared by cycling the  $\overline{\text{SD}}$  pin.
  - To recover automatically from this fault, connect the  $\overline{\text{FAULT}}$  pin directly to the  $\overline{\text{SD}}$  pin.
- Thermal Protection:
  - When the die temperature exceeds 150°C ( $\pm 15^\circ\text{C}$ ) the device enters the shutdown state and the amplifier outputs are disabled. The TPA3111D1-Q1 device recovers automatically when the temperature decreases by 15°C.

The functional modes of the TPA3111D1-Q1 device are as follows:

- Gain setting:
  - The gain of the TPA3111D1-Q1 device is set to one of four options by the state of the GAIN0 and GAIN1 pins. Changing the gain setting also changes the input impedance of the TPA3111D1-Q1 device.
  - Refer to [Table 2](#) for a list of the gain settings.
- Shutdown Mode:
  - The  $\overline{\text{SD}}$  pin can be used to enter the shutdown mode which mutes the amplifier and causes the TPA3111D1-Q1 device to enter a low-current state. This mode can also be triggered to improve power-off pop performance.
- PLIMIT:
  - The PLIMIT pin limits the output peak-to-peak voltage based on the voltage supplied to the PLIMIT pin. The peak output voltage is limited to four times the voltage at the PLIMIT pin.

The [Feature Description](#) and [Device Functional Modes](#) sections provide more details about these functions.

## 7.2 Functional Block Diagram



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## 7.3 Feature Description

### 7.3.1 DC Detect

The TPA3111D1-Q1 circuitry protects the speakers from DC current which might occur because of defective capacitors on the input or shorts on the printed circuit board at the inputs. A DC-detect fault is reported on the FAULT pin as a low state. The DC-detect fault also causes the amplifier to shut down by changing the state of the outputs to Hi-Z. To clear the DC detect, cycle the PVCC supply. Cycling SD does NOT clear a DC-detect fault.

A DC-detect fault is issued when the output differential duty-cycle exceeds 14% (for example, 57%, -43%) for more than 420 ms at the same polarity. This feature helps protect the speaker from large DC currents or AC currents less than 2 Hz. To avoid nuisance faults because of the DC detect circuit, hold the SD pin low at power-up until the signals at the inputs are stable. Also, match the impedance at the positive and negative input to avoid nuisance DC-detect faults.

Table 1 lists the minimum differential input voltages required to trigger the DC detect. The inputs must remain at or above the voltage listed in the table for more than 420 ms to trigger the DC detect.

Table 1. DC Detect Threshold

AV (dB)	V <sub>IN</sub> (mV, DIFFERENTIAL)
20	112
26	56
32	28
36	17

### 7.3.2 Short-Circuit Protection and Automatic Recovery Feature

The TPA3110D2-Q1 device has protection from overcurrent conditions caused by a short circuit on the output stage. The short-circuit protection fault is reported on the  $\overline{\text{FAULT}}$  pin as a low state. The amplifier outputs are switched to a Hi-Z state when the short circuit-protection latch is engaged. The latch is cleared by cycling the  $\overline{\text{SD}}$  pin through the low state.

If automatic recovery from the short-circuit protection latch is desired, connect the  $\overline{\text{FAULT}}$  pin directly to the  $\overline{\text{SD}}$  pin. This allows the  $\overline{\text{FAULT}}$  pin function to automatically drive the  $\overline{\text{SD}}$  pin low, which clears the short-circuit protection latch.

### 7.3.3 Thermal Protection

Thermal protection on the TPA3111D1-Q1 device prevents damage to the device when the internal die temperature exceeds 150°C. This trip point has a  $\pm 15^\circ\text{C}$  tolerance from device to device. When the die temperature exceeds the thermal set point, the device enters the shutdown state and the outputs are disabled. This is not a latched fault. The thermal fault is cleared once the temperature of the die is reduced by 15°C. The device begins normal operation at this point with no external system interaction.

Thermal protection faults are NOT reported on the  $\overline{\text{FAULT}}$  pin.

### 7.3.4 GVDD Supply

The GVDD supply powers the gates of the output full bridge transistors. The GVDD supply can also supply the PLIMIT voltage divider circuit. Add a 1- $\mu\text{F}$  capacitor to ground at this pin.

## 7.4 Device Functional Modes

### 7.4.1 Gain Setting Through Gain0 and Gain1 Inputs

The gain of the TPA3111D1-Q1 device is set by two input pins, GAIN0 and GAIN1. The voltage slew rate of these gain pins, along with pins 1 and 14, must be restricted to no more than 10 V/ms. For higher slew rates, use a 100-k $\Omega$  resistor in series with the pins.

The gains listed in [Table 2](#) are realized by changing the taps on the input resistors inside the amplifier which causes the input impedance ( $Z_i$ ) to be dependent on the gain setting. The actual gain settings are controlled by ratios of resistors, so the gain variation from part-to-part is small. However, the input impedance from part-to-part at the same gain may shift by  $\pm 20\%$  because of shifts in the actual resistance of the input resistors.

For design purposes, the input network (discussed in the [Input Resistance](#) section) should be designed assuming an input impedance of 7.2 k $\Omega$ , which is the absolute minimum input impedance of the TPA3111D1-Q1 device. At the lower gain settings, the input impedance could increase as high as 72 k $\Omega$ .

**Table 2. Gain Setting**

GAIN1	GAIN0	AMPLIFIER GAIN (dB)	INPUT IMPEDANCE (k $\Omega$ )
		TYPICAL	TYPICAL
0	0	20	60
0	1	26	30
1	0	32	15
1	1	36	9

### 7.4.2 $\overline{SD}$ Operation

The TPA3111D1-Q1 device employs a shutdown mode of operation designed to reduce supply current ( $I_{CC}$ ) to the absolute minimum level during periods of non-use for power conservation. The  $\overline{SD}$  input pin should be held high (see the *AC Characteristics:  $V_{CC} = 24 V$*  and *AC Characteristics:  $V_{CC} = 12 V$*  tables for the trip point values) during normal operation when the amplifier is in use. Pulling the  $\overline{SD}$  pin low causes the outputs to mute and the amplifier to enter a low-current state. Never leave the  $\overline{SD}$  pin unconnected. Amplifier operation is unpredictable if the  $\overline{SD}$  pin is not connected.

For the best power-off pop performance, place the amplifier in the shutdown mode prior to removing the power supply voltage.

### 7.4.3 PLIMIT

The voltage at the PLIMIT pin (pin 10) can limit the power to levels below that which is possible based on the supply rail. Add a resistor divider from the GVDD pin to ground to set the voltage at the PLIMIT pin. An external reference can also be used if tighter tolerance is required. Also add a 1- $\mu F$  capacitor from the PLIMIT pin to ground.

The PLIMIT circuit sets a limit on the output peak-to-peak voltage. This limit can be thought of as a virtual voltage rail, which is lower than the supply connected to PVCC. This virtual rail is four times the voltage at the PLIMIT pin. This output voltage can be used to calculate the maximum output power for a given maximum input voltage and speaker impedance.

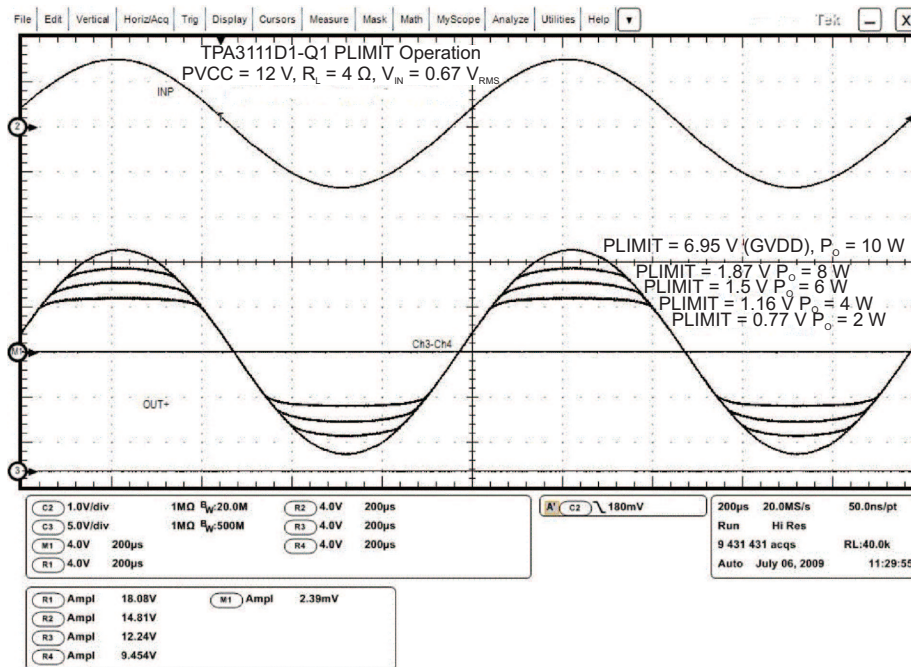


Figure 15. PLIMIT Circuit Operation

The PLIMIT circuit sets a limit on the output peak-to-peak voltage. The limiting occurs by limiting the duty cycle to the fixed maximum value. This limit can be thought of as a virtual voltage rail which is lower than the supply connected to PVCC. This virtual rail is four times the voltage at the PLIMIT pin. This output voltage can be used to calculate the maximum output power for a given maximum input voltage and speaker impedance. Use Equation 1 to calculate the maximum power output ( $P_{OUT}$ ).

$$P_{OUT} = \frac{\left( \left( \frac{R_L}{R_L + 2 \times R_S} \right) \times V_P \right)^2}{2 \times R_L} \quad \text{for unclipped power}$$

where

- $R_S$  is the total series resistance including  $R_{DS(on)}$ , and any resistance in the output filter.
- $R_L$  is the load resistance.
- $V_P$  is the peak amplitude of the output possible within the supply rail.
- $V_P = 4 \times \text{PLIMIT}$  voltage if  $\text{PLIMIT} < 4 \times V_P$
- $P_{OUT}(10\%THD) = 1.25 \times P_{OUT}(\text{unclipped})$

(1)

**Table 3. PLIMIT Typical Operation**

TEST CONDITIONS	PLIMIT VOLTAGE	OUTPUT POWER (W)	OUTPUT VOLTAGE AMPLITUDE ( $V_{p,p}$ )
PVCC = 24 V, $V_{IN} = 1 V_{RMS}$ , $R_L = 4 \Omega$ , Gain = 20 dB	1.92	10	15
PVCC = 24 V, $V_{IN} = 1 V_{RMS}$ , $R_L = 4 \Omega$ , Gain = 20 dB	1.24	5	10
PVCC = 12 V, $V_{IN} = 1 V_{RMS}$ , $R_L = 4 \Omega$ , Gain = 20 dB	1.75	10	15.3
PVCC = 12 V, $V_{IN} = 1 V_{RMS}$ , $R_L = 4 \Omega$ , Gain = 20 dB	1.20	5	10.3

## 8 Application and Implementation

### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 8.1 Application Information

The TPA3111D1-Q1 device is an automotive class-D audio amplifier. The device accepts either a single ended or differential analog input, amplifies the signal, and drives up to 10 W across a bridge tied load, usually a speaker. Because an analog input is required, this device is often paired with a codec or audio DAC if the audio source is digital.

The four digital I/O pins, GAIN0, GAIN1,  $\overline{SD}$ , and  $\overline{FAULT}$ , can be pulled up to the PVCC supply. When connecting these pins to the PVCC supply, a 100-k $\Omega$  resistor must be put in series to limit the slew rate. For more information, see *Maximum Slew Rate on High-Voltage Pins for TPA3111D1 (SLUA626)*. One of four gain settings is used depending on the configuration of GAIN0 and GAIN1. The  $\overline{SD}$  pin is used to put the device in shutdown or normal mode. The  $\overline{FAULT}$  pin is used to indicate if a DC detect or short circuit fault was detected. See the *Typical Application* section for design considerations and how to select external components.

### 8.2 Typical Application

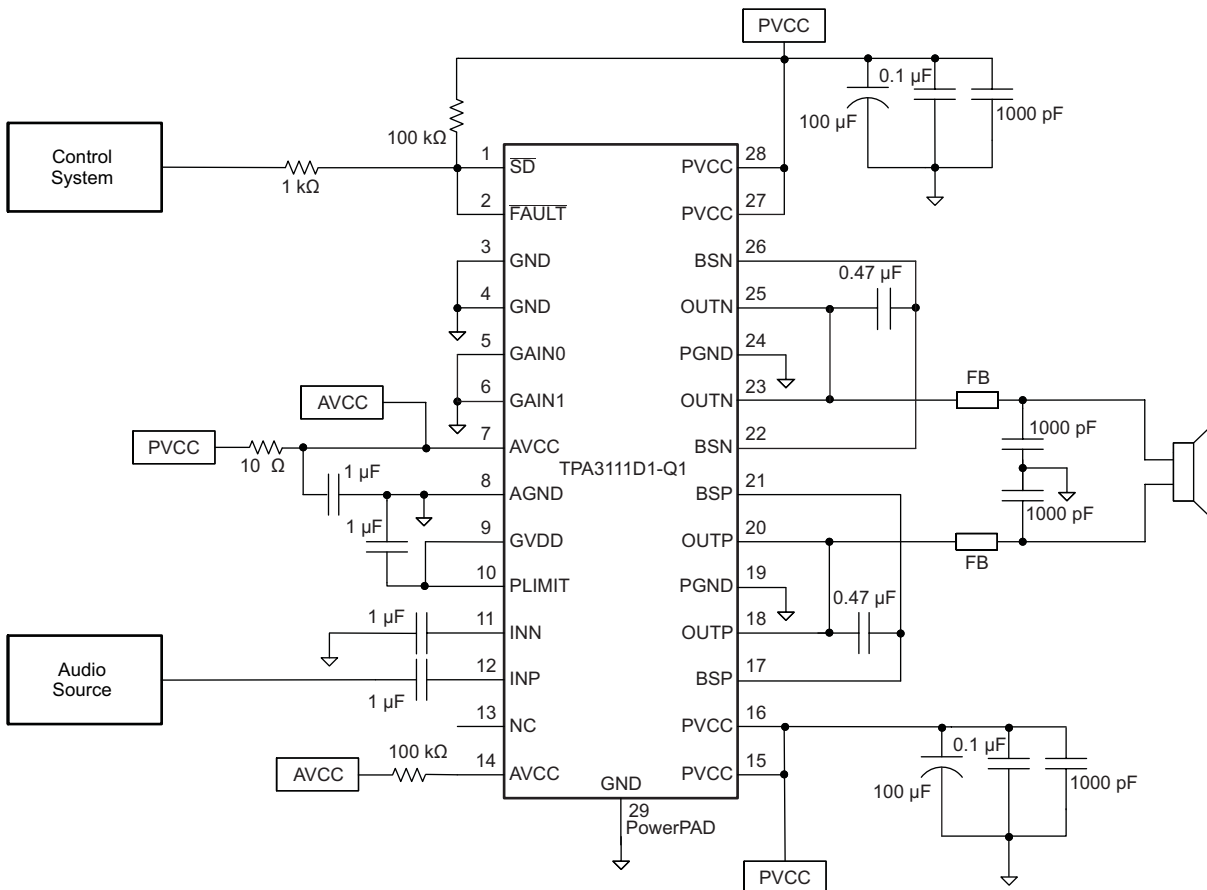


Figure 16. Mono Class-D Amplifier With BTL Output

## Typical Application (continued)

### 8.2.1 Design Requirements

The typical requirements for designing the external components around the TPA3111D1-Q1 device include efficiency, EMI performance, and EMC performance. For most applications, only a ferrite bead is required to filter unwanted emissions. The ripple current is low enough that an LC filter is typically not needed. As the output power is increased, causing the ripple current to increase, an LC filter can be added to improve efficiency. An LC filter can also be added in cases where additional EMI suppression is needed.

In addition to discussing how to select a ferrite bead and when to use an LC filter, the [Detailed Design Procedure](#) section also discusses the input filter and power supply decoupling. The input filter must be selected with the input impedance of the amplifier in mind. The cut-off frequency should be selected so that bass performance is not impacted. Power supply decoupling is important to ensure that noise from the power line does not impact the audio quality of the amplifier output.

### 8.2.2 Detailed Design Procedure

#### 8.2.2.1 Class-D Operation

This section focuses on the Class-D operation of the TPA3111D1-Q1 device.

#### 8.2.2.2 TPA3111D1-Q1 Modulation Scheme

The TPA3111D1-Q1 device uses a modulation scheme that allows operation without the classic LC reconstruction filter when the amplifier is driving an inductive load. Each output is switching from 0 V to the supply voltage. The OUPN and OUTN pins are in phase with each other with no input so that there is little or no current in the speaker. The duty cycle of the OUPN pin is greater than 50% and the duty cycle of the OUTN pin is less than 50% for positive output voltages. The duty cycle of the OUPN pin is less than 50% and the duty cycle of the OUTN pin is greater than 50% for negative output voltages. The voltage across the load sits at 0 V throughout most of the switching period, greatly reducing the switching current, which reduces any  $I^2R$  losses in the load. See [Figure 20](#) for a plot of the output waveforms.

#### 8.2.2.3 Ferrite Bead Filter Considerations

Using the advanced emissions suppression technology in the TPA3111D1-Q1 amplifier, designing a high efficiency Class-D audio amplifier is possible while minimizing interference to surrounding circuits. This design can also be accomplished with only a low-cost ferrite bead filter. In this case, the ferrite bead used in the filter must be carefully selected.

One important aspect of the ferrite bead selection is the type of material used in the ferrite bead. Not all ferrite material is alike, therefore select a material that is effective in the 10-MHz to 100-MHz range which is key to the operation of the Class-D amplifier. Many of the specifications regulating consumer electronics have emissions limits as low as 30 MHz. Use the ferrite bead filter to block radiation in the 30-MHz and above range from appearing on the speaker wires and the power supply lines which are good antennas for these signals. The impedance of the ferrite bead can be used along with a small capacitor with a value in the range of 1000 pF to reduce the frequency spectrum of the signal to an acceptable level. For best performance, the resonant frequency of the ferrite bead and capacitor filter should be less than 10 MHz.

Also, ensure that the ferrite bead is large enough to maintain the impedance at the peak currents expected for the amplifier. Some ferrite bead manufacturers specify the bead impedance at a variety of current levels. In this case, ensure that the ferrite bead maintains an adequate amount of impedance at the peak current the amplifier sees. If these specifications are not available, estimate the bead current handling capability by measuring the resonant frequency of the filter output at very low power and at maximum power. A change of resonant frequency of less than 50% under this condition is desirable. Examples of tested ferrite beads that work well with the TPA3111D2-Q1 device include 28L0138-80R-10 and HI1812V101R-10 from Steward and the 742792510 from Würth Electronics.

A high-quality ceramic capacitor is also required for the ferrite bead filter. A low-ESR capacitor with good temperature and voltage characteristics works best.



## Typical Application (continued)

Additional EMC improvements can be obtained by adding snubber networks from each of the Class-D outputs to ground. The suggested values for a simple RC series snubber network is a 10-Ω resistor in series with a 330-pF capacitor, although the design of the snubber network is specific to every application and must consider the parasitic reactance of the printed circuit board as well as the audio amplifier. Take care to evaluate the stress on the component in the snubber network especially if the amplifier is running at a high PVCC supply. Also, ensure the layout of the snubber network is tight and returns directly to the PGND pin or the PowerPAD beneath the chip.

### 8.2.2.4 Efficiency: LC Filter Required With the Traditional Class-D Modulation Scheme

The main reason that the traditional Class-D amplifier needs an output filter is because the switching waveform results in maximum current flow, which causes more loss in the load resulting in lower efficiency. The ripple current is large for the traditional modulation scheme, because the ripple current is proportional to voltage multiplied by the time at that voltage. The differential voltage swing is  $2 \times V_{CC}$ , and the time at each voltage is half the period for the traditional modulation scheme. An ideal LC filter is required to store the ripple current from each half cycle for the next half cycle, while any resistance causes power dissipation. The speaker is both resistive and reactive, whereas an LC filter is almost purely reactive.

The TPA3111D1-Q1 modulation scheme has little loss in the load without a filter because the pulses are short and the change in voltage is  $V_{CC}$  instead of  $2 \times V_{CC}$ . As the output power increases, the pulses widen, making the ripple current larger. Ripple current can be filtered with an LC filter for increased efficiency, but for most applications the filter is not required.

An LC filter with a cutoff frequency less than the Class-D switching frequency allows the switching current to flow through the filter instead of the load. The filter has less resistance but higher impedance at the switching frequency than the speaker, which results in less power dissipation, therefore increasing efficiency.

### 8.2.2.5 When to Use an Output Filter for EMI Suppression

The TPA3111D1-Q1 device has been tested with a simple ferrite bead filter for a variety of applications including long speaker wires up to 125 cm and high power. The TPA3111D1EVM passes FCC Class-B specifications under these conditions using twisted speaker wires. The size and type of ferrite bead can be selected to meet application requirements. Also, the filter capacitor can be increased if necessary with some impact on efficiency.

A few circuit instances may require the addition of a complete LC reconstruction filter. These circumstances might occur if nearby circuits are very sensitive to noise. In these cases a classic second order Butterworth filter similar to those shown in the following figures can be used.

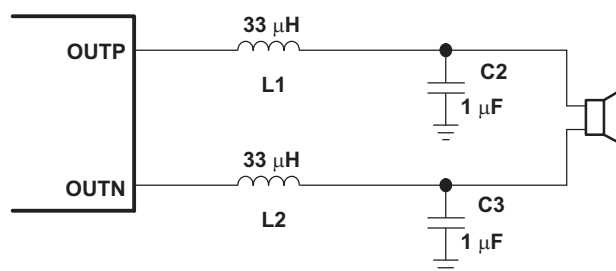
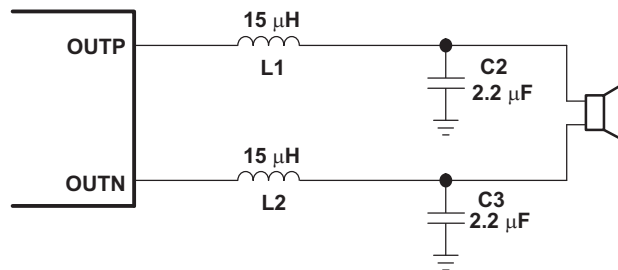
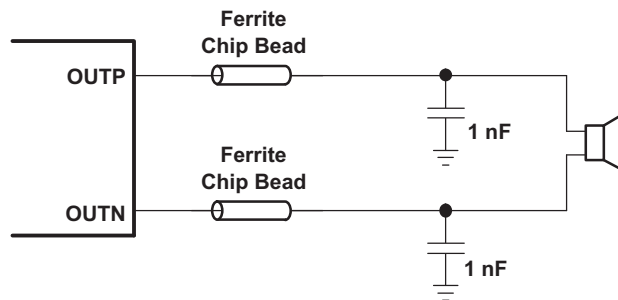
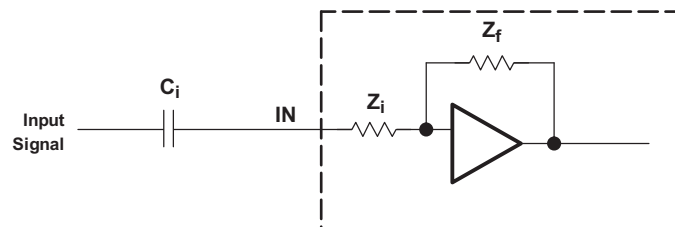


Figure 17. Typical LC Output Filter, Cutoff Frequency of 27 kHz, Speaker Impedance = 8 Ω

**Typical Application (continued)**

**Figure 18. Typical LC Output Filter, Cutoff Frequency of 27 kHz, Speaker Impedance = 4 Ω**

**Figure 19. Typical Ferrite Chip Bead Filter (Chip Bead Example: Steward HI0805R800R-10)**
**8.2.2.6 Input Resistance**

Changing the gain setting can vary the input resistance of the amplifier from the smallest value, 9 kΩ ±20%, to the largest value, 60 kΩ ±20%. As a result, if a single capacitor is used in the input high-pass filter, the –3 dB or cutoff frequency may change when changing gain steps.



Use [Equation 2](#) to calculate the –3-dB frequency . Use the values listed in [Table 2](#) for Zi.

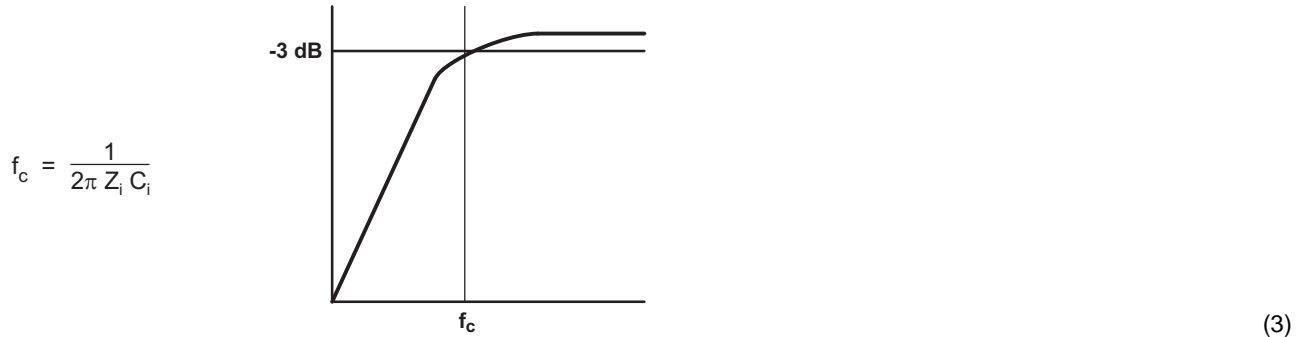
$$f = \frac{1}{2\pi Z_i C_i}$$

(2)

## Typical Application (continued)

### 8.2.2.7 Input Capacitor, $C_i$

In the typical application, an input capacitor ( $C_i$ ) is required to allow the amplifier to bias the input signal to the proper DC level for optimum operation. In this case,  $C_i$  and the input impedance of the amplifier ( $Z_i$ ) form a high-pass filter with the corner frequency determined in Equation 3.



The value of  $C_i$  is important, as it directly affects the bass (low-frequency) performance of the circuit. Consider the example where  $Z_i$  is 60 k $\Omega$  and the specification calls for a flat bass response down to 20 Hz. Equation 3 is reconfigured as Equation 4.

$$C_i = \frac{1}{2\pi Z_i f_c}$$

(4)

In this example,  $C_i$  is 0.13  $\mu\text{F}$ ; so, one would likely choose a value of 0.15  $\mu\text{F}$  as this value is commonly used. If the gain is known and is constant, use  $Z_i$  from Table 2 to calculate  $C_i$ . A further consideration for this capacitor is the leakage path from the input source through the input network ( $C_i$ ) and the feedback network to the load. This leakage current creates a DC offset voltage at the input to the amplifier that reduces useful headroom, especially in high gain applications. For this reason, a low-leakage tantalum or ceramic capacitor is the best selection. If a ceramic capacitor is used, use a high quality capacitor with good temperature and voltage coefficient. An X7R-type capacitor works well and, if possible, use a higher voltage rating than required which provides a better C-versus-voltage characteristic. When polarized capacitors are used, the positive side of the capacitor should face the amplifier input in most applications as the DC level there is held at 3 V, which is likely higher than the source DC level. Note that it is important to confirm the capacitor polarity in the application. Additionally, lead-free solder can create DC offset voltages. Ensure that boards are cleaned properly.

### 8.2.2.8 BSN and BSP Capacitors

The full H-bridge output stage uses only NMOS transistors. Therefore, they require bootstrap capacitors for the high side of each output to turn on correctly. A 470-nF ceramic capacitor, rated for at least 16 V, must be connected from each output to its corresponding bootstrap input. Specifically, one 470-nF capacitor must be connected from OUTP to BSP, and one 470-nF capacitor must be connected from OUTN to BSN. See the simplified application circuit diagram in the 说明 section.

The bootstrap capacitors connected between the BSx pins and corresponding output function as a floating power supply for the high-side N-channel power MOSFET gate drive circuitry. During each high-side switching cycle, the bootstrap capacitors hold the gate-to-source voltage high enough to keep the high-side MOSFETs turned on.

### 8.2.2.9 Differential Inputs

The differential input stage of the amplifier cancels any noise that appears on both input lines of the channel. To use the TPA3111D1-Q1 device with a differential source, connect the positive lead of the audio source to the INP input and the negative lead from the audio source to the INN input. To use the TPA3111D1-Q1 device with a single-ended source, AC-ground the INP or INN input through a capacitor equal in value to the input capacitor on INN or INP and apply the audio source to either input. In a single-ended input application, the unused input should be AC-grounded at the audio source instead of at the device input for best noise performance. For good transient performance, the impedance seen at each of the two differential inputs should be the same.

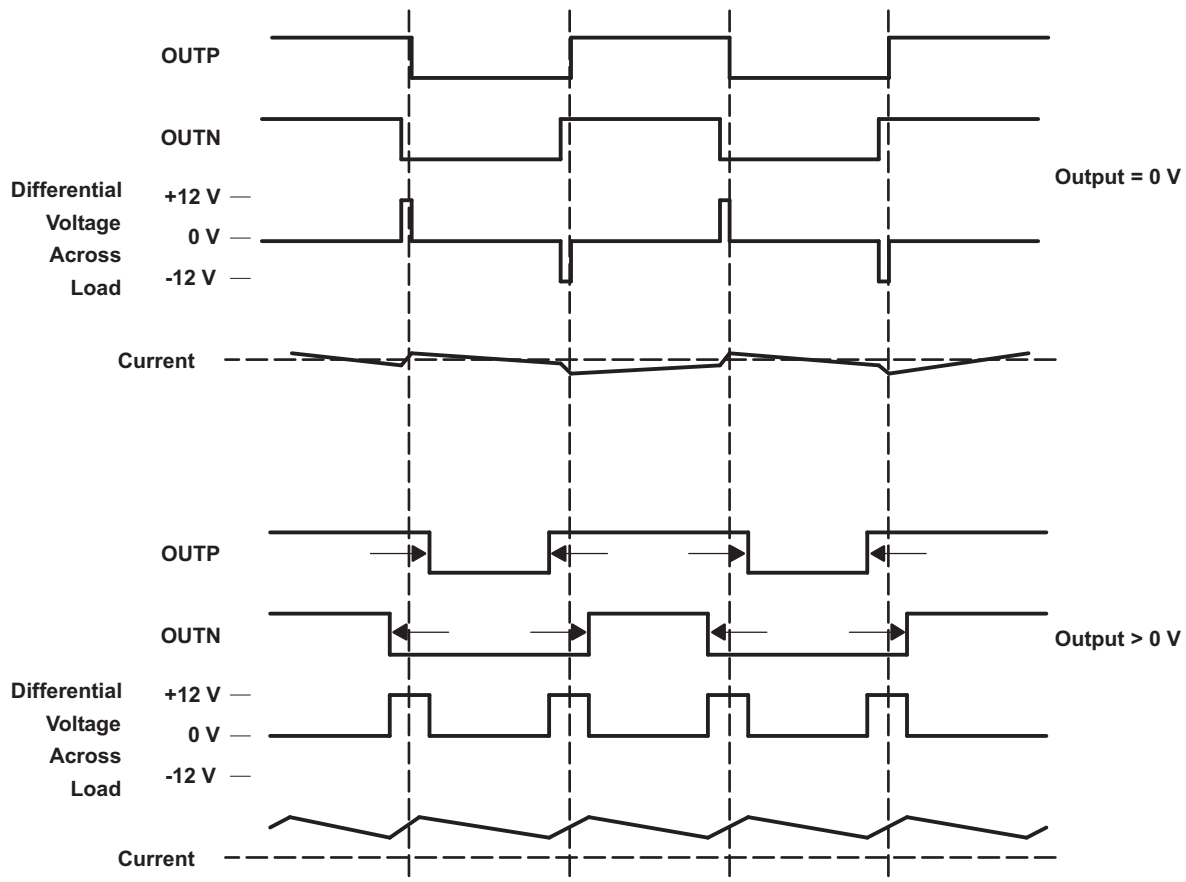
## Typical Application (continued)

The impedance at the inputs should be limited to an RC time constant of 1 ms or less if possible. Limiting the impedance allows the input DC blocking capacitors to become completely charged during the 14-ms power-up time. If the input capacitors are not allowed to completely charge, some additional sensitivity to component matching can occur which can result in a pop if the input components are not well matched.

### 8.2.2.10 Using Low-ESR Capacitors

Low-ESR capacitors are recommended throughout this application. A real (as opposed to ideal) capacitor can be modeled simply as a resistor in series with an ideal capacitor. The voltage drop across this resistor minimizes the beneficial effects of the capacitor in the circuit. The lower the equivalent value of this resistance, the more the real capacitor behaves like an ideal capacitor.

### 8.2.3 Application Curve



**Figure 20. The TPA3111D1-Q1 Output Voltage and Current Waveforms into an Inductive Load**

## 9 Power Supply Recommendations

The TPA3111D1-Q1 device is a high-performance CMOS audio amplifier that requires adequate power supply decoupling to ensure that the output total harmonic distortion (THD) is as low as possible. Power supply decoupling also prevents oscillations for long lead lengths between the amplifier and the speaker.

Optimum decoupling is achieved by using a network of capacitors of different types that target specific types of noise on the power supply leads. For higher frequency transients due to parasitic circuit elements such as bond wire and copper trace inductances as well as lead frame capacitance, a good quality low equivalent-series-resistance (ESR) ceramic capacitor with a value between 220 pF and 1000 pF works well. This capacitor should be placed as close to the device PVCC pins and system ground (either PGND pins or PowerPAD) as possible.

For mid-frequency noise because of filter resonances or PWM switching transients as well as digital hash on the line, place another good quality capacitor, with a typical value of 0.1  $\mu$ F to 1  $\mu$ F, as close as possible to the PVCC pins which works best. For filtering lower frequency noise signals, a larger aluminum electrolytic capacitor with a value of 220  $\mu$ F or greater placed near the audio power amplifier is recommended. The 220- $\mu$ F capacitor also serves as a local storage capacitor for supplying current during large signal transients on the amplifier outputs. The PVCC pins provide the power to the output transistors, so a 220- $\mu$ F or larger capacitor should be placed on each PVCC pin. A 10- $\mu$ F capacitor on the AVCC pin is adequate. Also, a small decoupling resistor between the AVCC and PVCC pins can be used to keep high frequency Class-D noise from entering the linear input amplifiers.

## 10 Layout

### 10.1 Layout Guidelines

The TPA3111D1-Q1 device can be used with a small, inexpensive ferrite bead output filter for most applications. However, because the Class-D switching edges are very fast, carefully planning the layout of the printed circuit board is important. Use the guidelines that follow to help meet the EMC requirements:

- The high-frequency decoupling capacitors should be placed as close to the PVCC and AVCC pins as possible. Large (220  $\mu$ F or greater) bulk power-supply decoupling capacitors should be placed near the TPA3111D1-Q1 device on the PVCC supplies. Local, high-frequency bypass capacitors should be placed as close to the PVCC pins as possible. These capacitors can be connected to the thermal pad directly for an excellent ground connection. Consider adding a small, good-quality low-ESR ceramic capacitor with a value between 220 pF and 1000 pF and a larger good-quality mid-frequency capacitor with a value between 0.1  $\mu$ F and 1  $\mu$ F to the PVCC connections at each end of the chip.
- Keep the current loop from each of the outputs through the ferrite bead and the small filter cap and back to PGND as small and tight as possible. The size of this current loop determines its effectiveness as an antenna.
- The ferrite EMI filter ([Figure 19](#)) should be placed as close to the output pins as possible for the best EMI performance. The LC filter ([Figure 17](#) and [Figure 18](#)) should be placed close to the outputs. The capacitors used in both the ferrite and LC filters should be grounded to power ground.
- The thermal pad must be soldered to the PCB for proper thermal performance and optimal reliability. The dimensions of the thermal pad and thermal land should be 6.46 mm by 2.35 mm. Seven rows of solid vias (three vias per row, 0.33 mm or 13 mils diameter) should be equally spaced underneath the thermal land. The vias should connect to a solid copper plane, either on an internal layer or on the bottom layer of the PCB. The vias must be solid vias, not thermal relief or webbed vias. See *PowerPAD™ Thermally Enhanced Package (SLMA002)* for more information on using the thermal pad of the package. For recommended PCB footprints, see the mechanical pages in the [机械、封装和可订购信息](#) section.

## 10.2 Layout Example

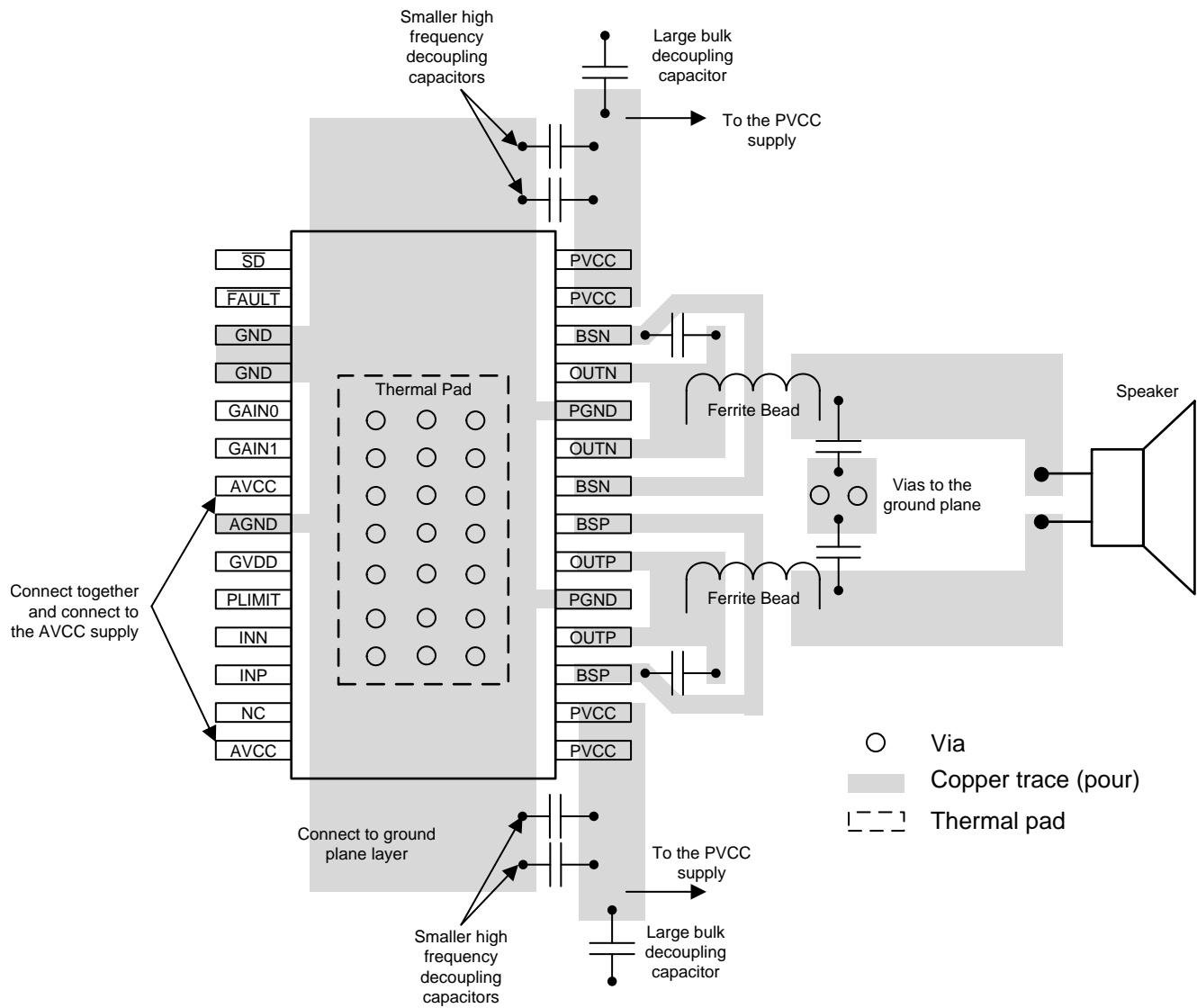


Figure 21. Recommended Layout

## 11 器件和文档支持

### 11.1 文档支持

#### 11.1.1 相关文档

相关文档请参阅以下部分：

- 《AN-1737 管理 D 类音频应用中的 EMI》，[SNAA050](#)
- 《AN-1849 音频放大器电源设计》，
- 《音频功率放大器性能测量指南》，[SLOA068](#)
- 《TPA3111D1 的高电压引脚上的最大转换率》，[SLUA626](#)
- 《PowerPAD™ 耐热增强型封装》，[SLMA002](#)
- 《TPA3111D1EVM 音频放大器评估板》，[SLOU270](#)
- 《TPA3110D2EVM 音频放大器评估板》，[SLOU263](#)
- 《对模拟组件使用热计算工具》，[SLUA566](#)

### 11.2 社区资源

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

**TI E2E™ Online Community** *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At [e2e.ti.com](#), you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

### 11.3 商标

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### 11.4 静电放电警告



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### 11.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 12 机械、封装和可订购信息

以下页中包括机械、封装和可订购信息。这些信息是针对指定器件可提供的最新数据。这些数据会在无通知且不对本文档进行修订的情况下发生改变。欲获得该数据表的浏览器版本，请查阅左侧的导航栏。

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPA3111D1QPWPRQ1	ACTIVE	HTSSOP	PWP	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR		TPA3111Q1	<b>Samples</b>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF TPA3111D1-Q1 :**

- Catalog: [TPA3111D1](#)

## NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPA3111D1QPWPRQ1	HTSSOP	PWP	28	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPA3111D1QPWRQ1	HTSSOP	PWP	28	2000	367.0	367.0	38.0

# MECHANICAL DATA

PWP (R-PDSO-G28)

PowerPAD™ PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusions. Mold flash and protrusion shall not exceed 0.15 per side.
  - This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
  - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
  - Falls within JEDEC MO-153

PowerPAD is a trademark of Texas Instruments.

# THERMAL PAD MECHANICAL DATA

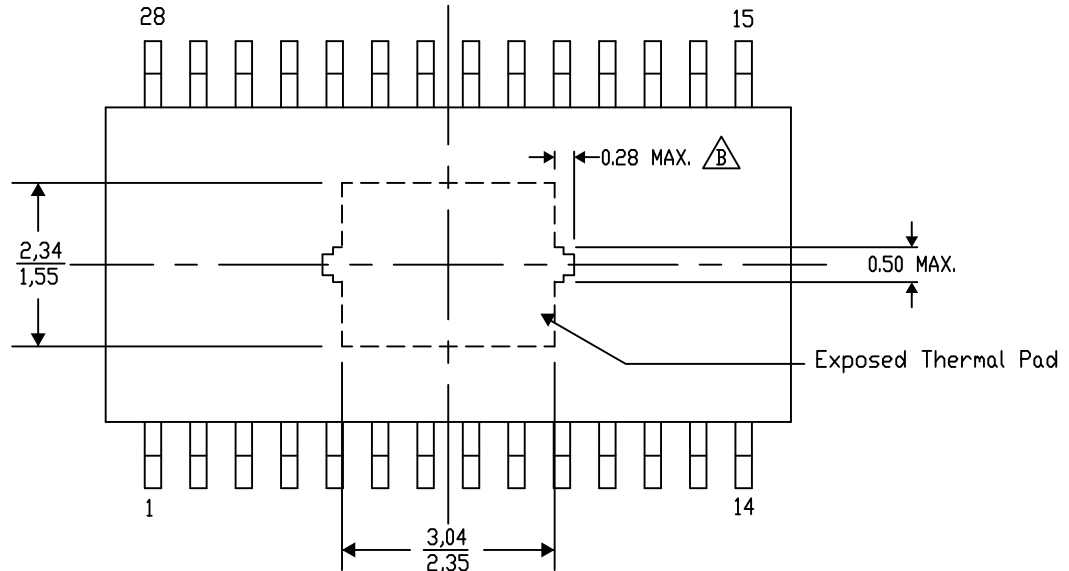
## PWP (R-PDSO-G28) PowerPAD™ SMALL PLASTIC OUTLINE

### THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.



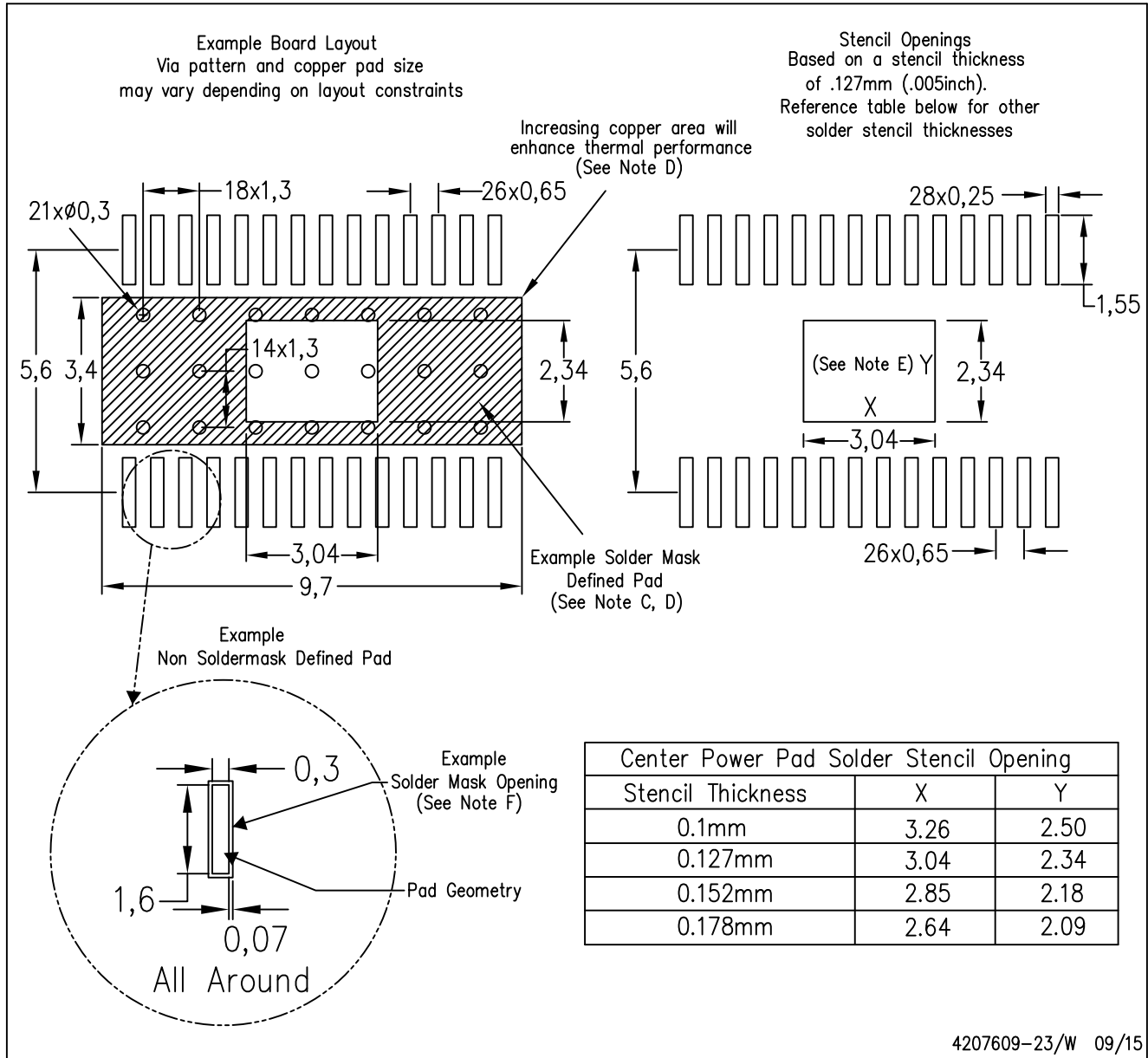
4206332-39/AO 01/16

NOTE: A. All linear dimensions are in millimeters  
⚠ Exposed tie strap features may not be present.

PowerPAD is a trademark of Texas Instruments

PWP (R-PDSO-G28)

PowerPAD™ PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>. Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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